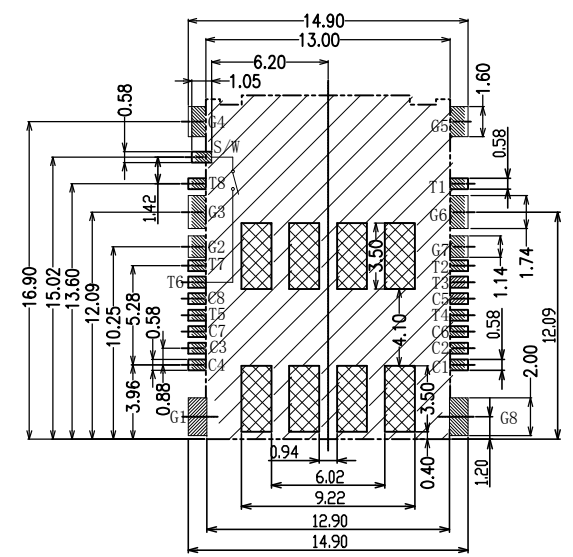
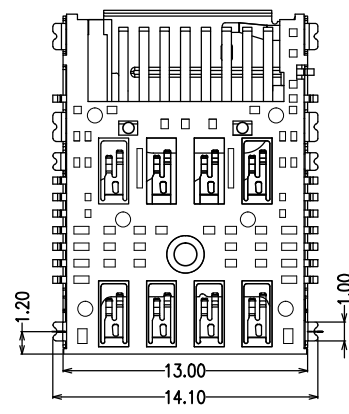
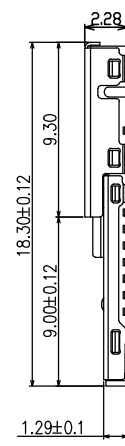
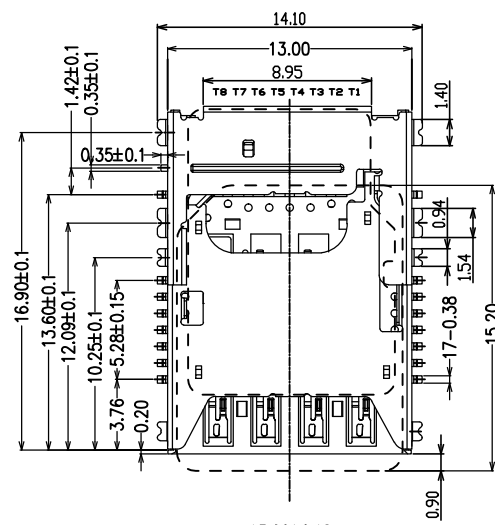
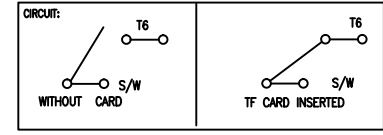
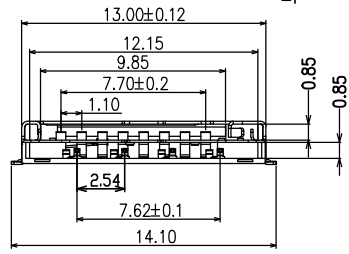


REV.	ECN.NO.	MODIFY.CONTENT	DATE
A		NEW	2018/11/29



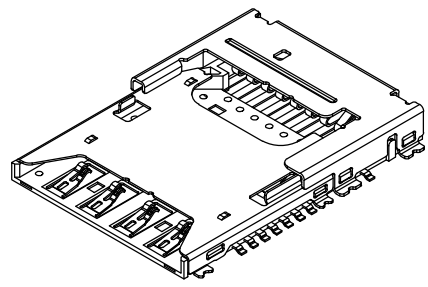
NO PATTERN AREA
 NO CIRCUIT AREA
 SOLDER AREA

P.C.B LAYOUT
(TOLERANCE±0.05)



NOTE:

- 一.材质及电镀方式 (MATERIAL AND FINISH)
- 1.塑胶 (HOUSING):LCP, UL 94V-0 , COLOR:BLACK
 - 2.端子 (CONTACT):COPPER ALLOY
GOLD FLASH PLATING ON CONTACT AREA,
GOLD FLASH PLATING ON SOLDER TAILS
50u" NICKEL UNDER PLATING OVER ALL
 - 3.铁壳 (SHELL):SUS304-3/4H
40u" NICKEL UNDER PLATING OVER ALL



二.机械特性 (MECHANICAL CHARACTERISTICS)

- 1.插入力 (Insertion Force):2.0Kgf Max
- 2.拔出力 (Withdrawal Force):0.1Kgf Min
- 3.耐久性 (Durability):5000次

三.电气特性

- 1.额定电流 (Current rating):1.0A AC/DC
- 2.接触电阻 (Contact resistance):100mΩ MAX
- 3.绝缘电阻 (Insulation resistance):500MΩ MIN
- 4.适用温度 (Operating temperature):-20℃~65℃

TF CARD PIN ASSIGNMENT

PIN NO.	PIN ASSIGNMENT
T1	DAT2
T2	CD/DAT3 ²
T3	CMD
T4	VDD
T5	CLK
T6	VSS
T7	DAT0
T8	DAT1

SIM pin assignment	
	Name
C1	VCC
C2	RST
C3	CLK
C4	Reserved
C5	GND
C6	VPP
C7	I/O
C8	Reserved

GENERAL TOLERANCE		DWG NO.	JYSA0525-009	APPD:	WIND	Scale	1:1
X.±0.45	x.'±5'	Title	2.28H 二合一卡座 平脚 (缺口外壳)	CHKD:		UNIT	mm
.X±0.35	.x'±2'	Part NO.	JYS-SIM228-192	DR:			
.XX±0.25	.xx'±1'			Date	2018/11/29		
.XXX±0.15	.xxx'±0.5'						
SHEET	1/1			Shenzhen		JYSCONN Electronics Co., LTD.	